

## A. Interconnect & Package 분과

Room H

하나스퀘어 (B115)

일 시 : 2월 16일(목) 11:20-12:35

세션명 : [TH2-A] 탄소 배선 및 TSV

좌 장 : 이원준(세종대학교), 이태운(연세대학교)

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- TH2-A-1 11:20-11:50 **[Invited]** Graphene Interconnects as Next Candidate for Replacing Cu Interconnects  
저자: Taeyoon Lee  
소속: Nanobio Device Laboratory, School of Electrical and Electronic Engineering, Yonsei University
- TH2-A-2 11:50-12:05 Growth of Multilayer Graphene by Chemical Vapor Deposition using Tetrabromomethane for Nanoscale Device Metallization  
저자: 최태진, 강혜민, 정한얼, 이현익, 홍주리, 이상근, 이태운, 김형준  
소속: 연세대학교 전기전자공학부
- TH2-A-3 12:05-12:20 Influence of Hydrogen Gases and Metal Induced Catalytic Effect for Graphene Etching  
저자: Hyonik Lee<sup>1</sup>, Juree Hong<sup>1</sup>, Jungmok Seo<sup>1</sup>, Sang Geun Lee<sup>1</sup>, Jae-Hong Lee<sup>1</sup>, Taejin Choi<sup>2</sup>, Hyemin Kang<sup>2</sup>, Jaehong Yoon<sup>2</sup>, Hanearl Jung<sup>2</sup>, Hyungjun Kim<sup>2</sup>, and Taeyoon Lee<sup>1</sup>  
소속: <sup>1</sup>Nanobio Device Laboratory, School of Electrical and Electronic Engineering, Yonsei University, <sup>2</sup>Nanodevice Laboratory, School of Electrical and Electronic Engineering, Yonsei University
- TH2-A-4 12:20-12:35 Cu Contamination under Thermal and Electric Field Stress and its Effect on the Pn<sup>+</sup> Diode Performances of the nMOSFET of a 3-D Integrated Circuit with through Silicon Vias  
저자: 연한울<sup>1</sup>, 정성엽<sup>1</sup>, 임정열<sup>1</sup>, 편정우<sup>2</sup>, 김형욱<sup>2</sup>, 백도현<sup>2</sup>, 주영창<sup>1</sup>  
소속: <sup>1</sup>서울대학교 재료공학부, <sup>2</sup>삼성전자 메모리사업부, 개발 QA팀